

IN THE CLAIMS

Please amend the claims as follows. This listing of claims replaces all prior versions and listings of claims in the application:

1. (Currently Amended) A run-to-run method for the computer-aided monitoring and controlling of a manufacturing process of a plurality of wafers, the method comprising the step of:

subjecting ~~subject~~ a plurality of wafers to at least one manufacturing step;

marking ~~mark~~ at least one of the processed wafers according to a deterministic selection criterion based on requirements of the run-to-run method and an inline SPC method, in such a way that the at least one marked wafer ~~it~~ can be subjected to an inline SPC measurement;

controlling the manufacturing process on the basis of the result of the inline SPC measurement of the wafer; and

selecting at least one wafer necessary for the run-to-run method and also for the inline SPC method according to the deterministic selection criterion.

2. (Original) The method as claimed in claim 1, in which the deterministic selection criterion is determined by means of rules.

3. (Currently Amended) A device for the monitoring and controlling of a manufacturing process of a plurality of wafers, the device comprising: ~~with~~

a processor which is set up to run steps of a run-to-run method; ~~the device comprising:~~

an element for carrying out at least one manufacturing step on the plurality of wafers;

an element for marking at least one of the plurality of wafers according to a deterministic selection criterion based on the run-to-run method and an inline SPC method, in such a way that the at least one marked wafer ~~it~~ can be subjected to an inline SPC measurement, and selecting at least one wafer ~~necessary~~ for the run-to-run

method and ~~also for the inline SPC method being selected~~ according to the deterministic selection criterion; and

an element for controlling the manufacturing process based on ~~the basis of~~ the result of the inline SPC measurement.

4. (Currently Amended) A computer-readable storage medium, in which a program for the monitoring and controlling of a manufacturing process of a plurality of wafers is stored, the monitoring and controlling being carried out by means of a run-to-run method, the program executing ~~which program executes the following~~ method steps when it is run by a processor, the computer-readable storage medium comprising:

a code for carrying out at least one manufacturing step on the wafers;

a code for marking at least one of the processed wafers according to a deterministic selection criterion based on the run-to-run method and an inline SPC method, in such a way that the at least one marked wafer ~~it~~ can be subjected to an inline SPC measurement; [[,]]

a code for selecting at least one wafer ~~necessary~~ for the run-to-run method and ~~also for the inline SPC method being selected~~ according to the deterministic selection criterion; and

a code for controlling the manufacturing process based on ~~the basis of~~ the result of the inline SPC measurement.

5. (Currently Amended) A program element for the monitoring and controlling of a manufacturing process of a plurality of wafers, the monitoring and controlling being carried out by means of a run-to-run method, the program element executing ~~which element executes the following~~ method steps when it is run by a processor, the program comprising:

code for carrying out at least one manufacturing step on the wafers;

code for marking at least one of the processed wafers according to a deterministic selection criterion based on the run-to-run method and an inline SPC method, in such a way that the at least one marked wafer ~~it~~ can be subjected to an inline SPC measurement; [[,]]

code for selecting at least one wafer ~~necessary~~ for the run-to-run method and ~~also for the inline SPC method being selected~~ according to the deterministic selection criterion; and

code for controlling the manufacturing process on based on the ~~basis of the~~ result of the inline SPC measurement.